TEMIC

TELEFUNKEN Semiconductors

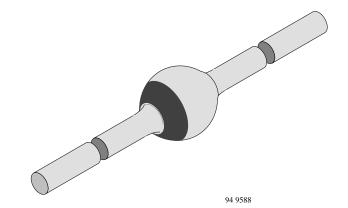
Very Fast Soft-Recovery Avalanche Rectifier

Features

- Glass passivated junction
- Hermetically sealed package
- Very low switching losses
- Low reverse current
- High reverse voltage



Switched mode power supplies High–frequency inverter circuits



Absolute Maximum Ratings

 $T_j = 25^{\circ}C$

Parameter	Test Conditions	Туре	Symbol	Value	Unit
Repetitive peak reverse voltage		BYM36A	V _{RRM}	200	V
		BYM36B	V _{RRM}	400	V
		BYM36C	V _{RRM}	600	V
		BYM36D	V _{RRM}	800	V
		BYM36E	V _{RRM}	1000	V
Reverse voltage		BYM36A	V_R	200	V
		BYM36B	V_{R}	400	V
		BYM36C	V_R	600	V
		BYM36D	V_{R}	800	V
		BYM36E	V_R	1000	V
Peak forward surge current	t _p =10ms, half sinewave		I _{FSM}	65	A
Average forward current		BYM36A BYM36B BYM36C	I _{FAV}	3	A
Average forward current		BYM36D BYM36E	I _{FAV}	2,9	A
Non repetitive reverse avalanche energy	I _{(BR)R} =400mA, inductive load		E_{R}	10	mJ
Junction temperature			Tj	175	°C
Storage temperature range			T _{stg}	-55+175	°C

TELEFUNKEN Semiconductors

Maximum Thermal Resistance

 $T_i = 25^{\circ}C$

Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	l=10mm, T _L =constant		25	K/W

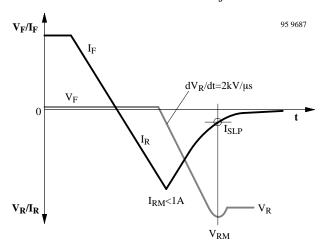
Characteristics

 $T_j = 25^{\circ}C$

Parameter	Test Conditions	Type	Symbol	Min	Тур	Max	Unit
Forward voltage	I _F =3A	BYM36A	V _F			1.6	V
		BYM36B	V _F			1.6	V
		BYM36C	V _F			1.6	V
		BYM36D	V_{F}			1.78	V
		ВҮМ36Е	V _F			1.78	V
	I _F =3A, T _j =175°C	BYM36A	V _F			1.22	V
	·	BYM36B	V_{F}			1.22	V
		BYM36C	V_{F}			1.22	V
		BYM36D	V_{F}			1.28	V
		ВҮМ36Е	V_{F}			1.28	V
Reverse current	$V_R = V_{RRM}$		I_R			5	μΑ
	$V_R = V_{RRM}, T_j = 150$ °C		I_R			100	μΑ
Reverse breakdown voltage	I _R =100μA	BYM36A	$V_{(BR)R}$	300			V
		BYM36B	$V_{(BR)R}$	500			V
		BYM36C	$V_{(BR)R}$	700			V
		BYM36D	$V_{(BR)R}$	900			V
		ВҮМ36Е	$V_{(BR)R}$	1100			V
Reverse recovery time	I _F =0.5A, I _R =1A, i _R =0.25A	BYM36A	t _{rr}			100	ns
		BYM36B	t _{rr}			100	ns
		BYM36C	t _{rr}			100	ns
		BYM36D	t _{rr}			150	ns
		ВҮМ36Е	t _{rr}			150	ns
Switching behaviour	I _F =2A, I _{RM} =1A, V _R =400V, Fig. 1		I_{SLP}			-200	mA

BYM36

Typical Characteristics $(T_j = 25^{\circ}C \text{ unless otherwise specified})$



TELEFUNKEN Semiconductors

Figure 1: $I_{\text{SLP-Definition}}$

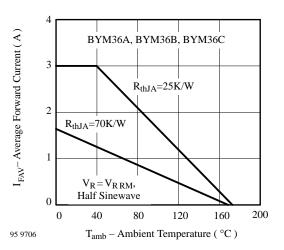


Figure 3: Average Forward Current vs. Ambient Temperature

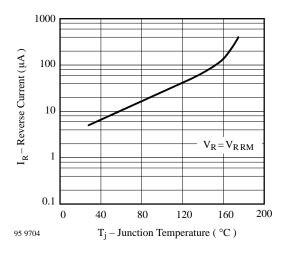


Figure 5: Reverse Current vs. Junction Temperature

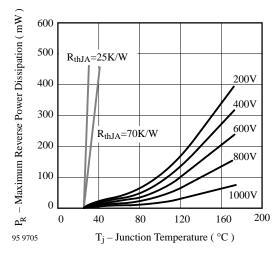


Figure 2 : Maximum Reverse Power Dissipation vs. Junction Temperature

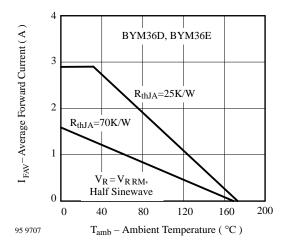


Figure 4: Average Forward Current vs. Ambient Temperature

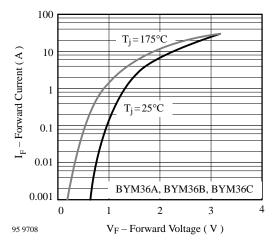


Figure 6: Forward Current vs. Forward Voltage

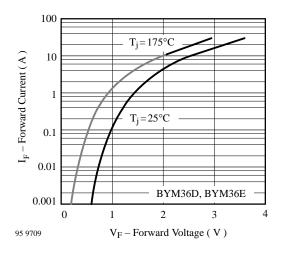
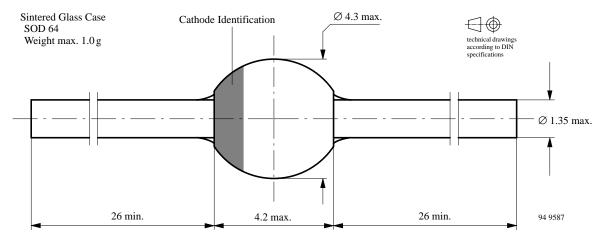


Figure 7 : Forward Current vs. Forward Voltage

Dimensions in mm



TELEFUNKEN Semiconductors

OZONE DEPLETING SUBSTANCES POLICY STATEMENT

It is the policy of TEMIC TELEFUNKEN microelectronic GmbH to

- 1. Meet all present and future national and international statutory requirements and
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

Of particular concern is the control or elimination of releases into the atmosphere of those substances which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) will soon severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of any ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA and
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with and do not contain ozone depleting substances.

We reserve the right to make changes to improve technical design without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

TEMIC TELEFUNKEN microelectronic GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany Telephone: 49 (0)7131 67 2831, Fax Number: 49 (0)7131 67 2423

Rev. A1: 12.12.1994 5